BQCSN-XXMF-XXXXT - 1.6x1.2 Crystals



FEATURES SMD Construction Standard 1.6x1.2mm Package Size

High Stability Over Temp

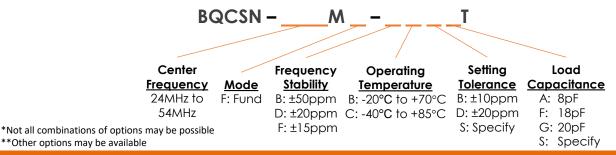
Crystals

0.018

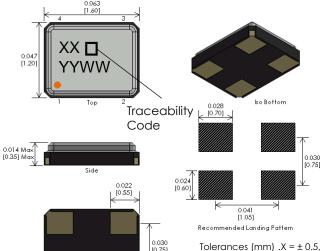
0.041

#blileytakesyoufurther

Part Number Configuration



Physical Specifications



PIN	FUNCTION
1	Crystal
2	Ground
3	Crystal
4	Ground

Tolerances (mm) $.X = \pm 0.5$, $.XX = \pm 0.2$ unless otherwise specified



- 1) Connection Pads: Gold(10-40 µ in.) over Nickel (100-250 µ in.)
 - 2) Weight = 1.5gms typical

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Performance Specifications

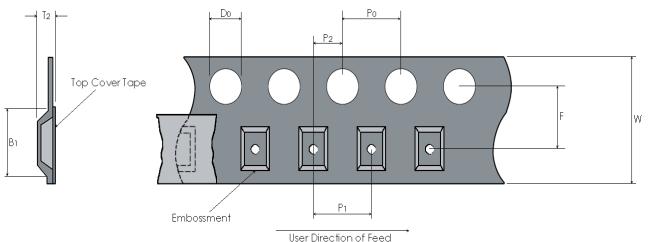
Parameter	Conditions	Values	Unit
Frequency Range		24.0 – 54.0	MHz
Frequency Tolerance	@ + 25°C	±50 Max (see options)	ppm
Frequency Stability		±100 Max (see options)	ppm
Aging	Max 1 st Year	±3.0	ppm
Equivalent Series Resistance (max)	24.0 – 30.0 MHz	150	Ω
	30.0 – 39.0 MHz	100	Ω
	40.0 – 54.0 MHz	80	Ω
Insulative Resistance	Min @ 100Vdc ±15Vdc	500	ΜΩ
Drive Level		10 Typ, 100 Max	μW
C0 (Shunt Capacitance)	Max	5.0	рF
CL (Load Capacitance)	Per Option (typical)	6-20 (see options)	рF
DLD	50nW to 100µW	±10 Max	ppm
RLD	50nW to 100µW	20% Max	Ω
Operating Temp Range		-20 to +70 / -40 to +85	°C
Storage Temp Range		-55 to +125	°C
Sealing Method		Seam Weld	
Moisture Sensitivity Level	1		

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Tape and Reel

Embossed Carrier Dimensions (8mm, 12mm, 16mm, 24mm Tape Only)



Tape Dimensions (mm) **Reel Dimensions (mm)** Do P1 P2 T2 Outside Dia. Parts / Reel 8 3.5 1.5 4.0 4 2.0 1.8 0.6 180 1,000

Recommended Reflow Profile

Reflow Profile: in accordance to IPC/JEDEC J-STD-020 (Latest Revision)

Additional Notes:

- This part has been designed for pick and place reflow soldering
- This part may be reflowed once
- This part should not be reflowed in the inverted position

Packaging

Packaging: All packaging must conform to ESD Controls detailed in ANSI/ESD S20.20 (Latest Revision)

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